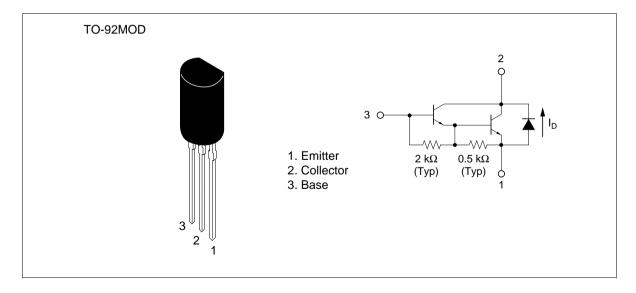
Silicon NPN Epitaxial, Darlington

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Application

- Low frequency power amplifier
- Complementary pair with 2SB1387

Outline





Absolute Maximum Ratings (Ta = 25° C)

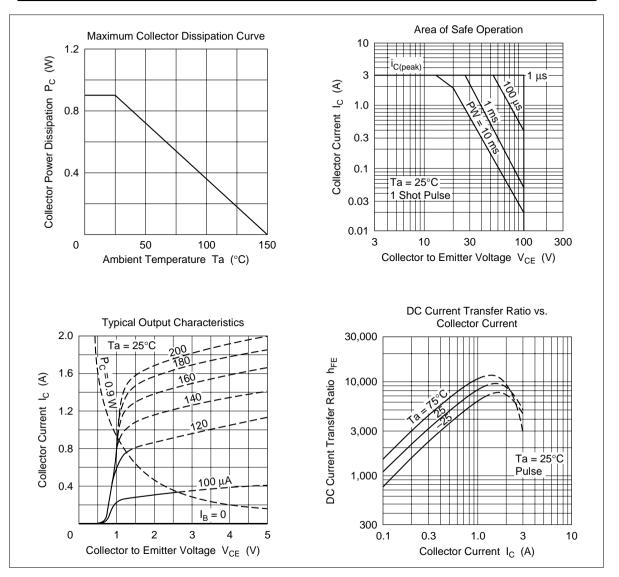
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	120	V
Collector to emitter voltage	V _{CEO}	120	V
Emitter to base voltage	V _{EBO}	7	V
Collector current	Ι _c	1.5	А
Collector peak current	ic _(peak)	3.0	А
Collector power dissipation	Pc	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I _D	1.5	А

Electrical Characteristics (Ta = 25°C)

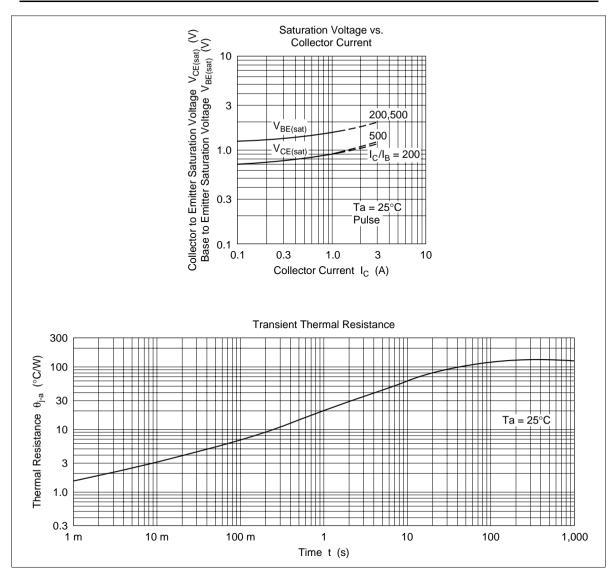
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	120	_	_	V	$I_{c} = 0.1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\rm (BR)CEO}$	120	—	—	V	$I_c = 10$ mA, $R_{\scriptscriptstyle BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{\rm E} = 50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	1.0	μΑ	$V_{CB} = 100 \text{ V}, \text{ I}_{E} = 0$
	I _{CEO}	—	—	10	μΑ	V_{CE} = 100 V, R_{BE} = ∞
DC current transfer ratio	h_{FE}	2000	—	30000		$V_{ce} = 3 V, I_c = 1 A^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)1}}$	—	—	1.5	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	V _{CE(sat)2}	—	—	2.0	V	$I_{c} = 1.5 \text{ A}, I_{B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	V _{BE(sat)1}	_	_	2.0	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	$V_{\text{BE(sat)2}}$	—	—	2.5	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
E to C diode forward voltage	V _D		_	3.0	V	$I_{\rm D} = 1.5 \ {\rm A}^{*1}$

Note: 1. Pulse test

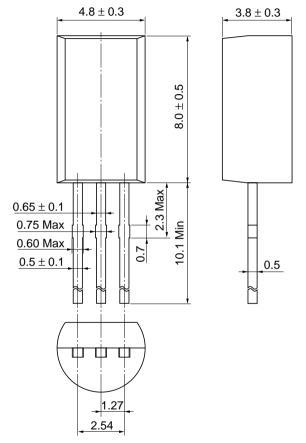
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Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 NorthAmerica URL http:semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg Europe http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi.com.hk/eng/bo/grp3/index.htm http://www.hitachi.co.jp/Sicd/indx.htm Japan For further information write to: Hitachi Semiconductor Hitachi Europe GmbH Hitachi Asia Pte. Ltd. (America) Inc. Electronic components Group 16 Collyer Quay #20-00 179 East Tasman Drive, Dornacher Stra§e 3 Hitachi Tower San Jose,CA 95134 D-85622 Feldkirchen, Munich Singapore 049318 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Germany Tel: 535-2100 Tel: <49> (89) 9 9180-0 Fax: 535-1533 Fax: <49> (89) 9 29 30 00

 Fax: <49> (89) 9 29 30 00
 Hita

 Hitachi Europe Ltd.
 Hita

 Electronic Components Group.
 Taip

 Whitebrook Park
 3F,

 Lower Cookham Road
 Tun

 Maidenhead
 Tel:

 Berkshire SL6 8YA, United Kingdom
 Fax

 Tel: <44> (1628) 585000

 Fax: <44> (1628) 778322

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

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Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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